

A cross-sectional view of a semiconductor device. A substrate 12 is covered by a layer 13. A layer labeled 'Co' is positioned above layer 13. Several rectangular blocks (14, 15, 16, 17) are placed on the 'Co' layer. A top layer 18 covers the entire structure. A side layer 11 is on the left. Electrical connections are shown: a terminal 't1' connected to block 14, a terminal 't2' connected to block 15, and a terminal connected to block 16. A voltage source 'V2' is connected to the left side of the device. A switch 'S2' is connected to terminal 't1'. A resistor 'Ro' is connected to terminal 't2'.

A cross-sectional view of a substrate 12. The substrate has a top surface 18 and a bottom surface 18. Two conductive patterns, 14 and 15, are formed on the top surface 18. The patterns are separated by a gap 17. Dashed lines indicate the vertical extent of the patterns.

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